

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1262	257/776	US-PGPUB;	OR	ON	2004/12/22-22:11
L2	2755	257/700	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 22:11
S1	39	(semiconductor or die or chip or IC) and dummy near via and dummy near (wirings or conductive or pattern)	USPAT	OR	ON	2004/12/22 13:37
S2	46	(semiconductor or die or chip or IC) and dummy near via and dummy near (wirings or conductive or pattern)	USPAT; JPO	OR	ON	2004/12/22 01:10
S3	0	"11350284"	JPO	OR	ON	2004/12/22 01:11
S4	0	"110350284"	JPO	OR	ON	2004/12/22 01:11
S5	0	"11350284"	JPO	OR	ON	2004/12/22 01:11
S6	1867	dielectric near constant with (silicon near dioxide)	USPAT	OR	OFF	2004/12/22 02:00
S7	1887	dielectric near constant with (silicon near nitride)	USPAT	OR	OFF	2004/12/22 02:06
S8	358	dielectric near constant with (SOG)	USPAT	OR	OFF	2004/12/22 02:06
S9	6167	dimension with via	USPAT	OR	ON	2004/12/22 13:38
S10	7164	(dimension or (cross-sectional or cross near sectional) near area) with via	USPAT	OR	ON	2004/12/22 13:39
S11	1065	((cross-sectional or cross near sectional) near area) with via	USPAT	OR	ON	2004/12/22 13:40
S12	7	S11 and ((cross-sectional or cross near sectional) near area) with via with normal	USPAT	OR	ON	2004/12/22 13:41
S13	0	( chip or die) and ((cross-sectional or cross near sectional) near area) with via with normal	USPAT	OR	ON	2004/12/22 13:41
S14	219	( chip or die) and ((cross-sectional or cross near sectional) near area) with via	USPAT	OR	ON	2004/12/22 14:09
S15	0	S14 and via with "microns.sub.-2"	USPAT	OR	ON	2004/12/22 14:21
S16	0	S14 and via with "\$.sub.-2"	USPAT	OR	ON	2004/12/22 13:50

S17	0	S14 and via with "sub.-2"	USPAT	OR	ON	2004/12/22 13:50
S18	0	S14 and via with "-2"	USPAT	OR	ON	2004/12/22 13:50
S19	6	"5,023,850".pn. or "4,551,857".pn. or "4,320,756".pn. or "5,934,226".pn. or "4,905,406".pn. or "5,901,666".pn.	USPAT	OR	ON	2004/12/22 13:55
S20	42	S14 and diameter with via	USPAT	OR	ON	2004/12/22 14:10
S21	0	S14 and via with "microns.sup.-2"	USPAT	OR	ON	2004/12/22 14:24
S22	0	S14 and via with ".sup.-2"	USPAT	OR	ON	2004/12/22 14:21
S23	0	S14 and via with "-2"	USPAT	OR	ON	2004/12/22 14:21
S24	0	S14 and via with ".sup."	USPAT	OR	ON	2004/12/22 14:21
S25	0	S11 and via with "microns.sup.-2"	USPAT	OR	ON	2004/12/22 14:22
S26	0	S11 and via with ".sup.-2"	USPAT	OR	ON	2004/12/22 14:22
S27	0	S11 and via same ".sup.-2"	USPAT	OR	ON	2004/12/22 14:22
S28	0	S11 and vias same ".sup.-2"	USPAT	OR	ON	2004/12/22 14:22
S29	0	".sup.-2"	USPAT	OR	ON	2004/12/22 14:22
S30	0	".sup.-2"	USPAT	OR	ON	2004/12/22 14:24
S31	0	"mu.m.sup.-2"	USPAT	OR	ON	2004/12/22 14:24
S32	0	"mu.m.sup."	USPAT	OR	ON	2004/12/22 14:24
S33	296570	"mu.m"	USPAT	OR	ON	2004/12/22 14:24
S34	35	S14 and via with (microns or "mu.m")	USPAT	OR	ON	2004/12/22 19:36
S35	5041	257/758	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 19:57
S36	3612	257/774	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 20:06
S37	1164	257/775	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 20:18